

5-A H-Bridge for DC-Motor Applications

TLE 5205-2



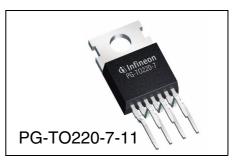


1 Overview

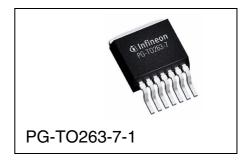
1.1 Features

- Delivers up to 5 A continuous 6 A peak current
- Optimized for DC motor management applications
- Operates at supply voltages up to 40 V
- Very low $R_{\rm DS~ON}$; typ. 200 m Ω @ 25 °C per switch
- · Output full short circuit protected
- Overtemperature protection with hysteresis and diagnosis
- Short circuit and open load diagnosis with open drain error flag
- Undervoltage lockout
- CMOS/TTL compatible inputs with hysteresis
- No crossover current
- Internal freewheeling diodes
- Wide temperature range; 40 °C < T_i < 150 °C
- · Green Product (RoHS compliant)
- AEC Qualified

Туре	Package
TLE 5205-2	PG-TO220-7-11
TLE 5205-2GP	PG-DSO-20-37
TLE 5205-2G	PG-TO263-7-1
TLE 5205-2S	PG-TO220-7-12









Description

The TLE 5205-2 is an integrated power H-bridge with DMOS output stages for driving DC-Motors. The part is built using the Infineon multi-technology process SPT[®] which allows bipolar and CMOS control circuitry plus DMOS power devices to exist on the same monolithic structure.

Operation modes forward (cw), reverse (ccw), brake and high impedance are invoked from just two control pins with TTL/CMOS compatible levels. The combination of an extremely low $R_{\rm DS~ON}$ and the use of a power IC package with low thermal resistance and high thermal capacity helps to minimize system power dissipation. A blocking capacitor at the supply voltage is the only external circuitry due to the integrated freewheeling diodes.



1.2 Pin Configuration (top view)

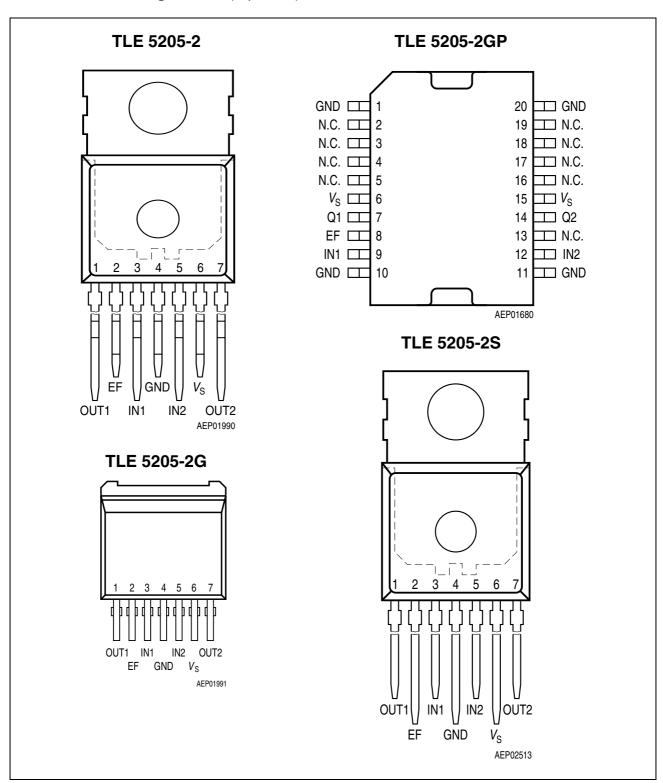


Figure 1 Pin Assigments



1.3 Pin Definitions and Functions

Pin No. P-TO220	Pin No. P-DSO	Symbol	Function				
1	7	OUT1	Output of Channel 1; Short-circuit protected; integrated freewheeling diodes for inductive loads.				
2	8	EF	Error Flag; TTL/CMOS compatible output for error detection; (open drain)				
3	9	IN1	Control Input 1; TTL/CMOS compatible				
4	1, 10, 11, 20	GND	Ground; internally connected to tab				
5	12	IN2	Control Input 2; TTL/CMOS compatible				
6	6, 15	V_{S}	Supply Voltage; block to GND				
7	14	OUT2	Output of Channel 2; Short-circuit protected; integrated freewheeling diodes for inductive loads.				
_	2, 3, 4, 5, 16, 17, 18, 19	N.C.	Not Connected				



1.4 Functional Block Diagram

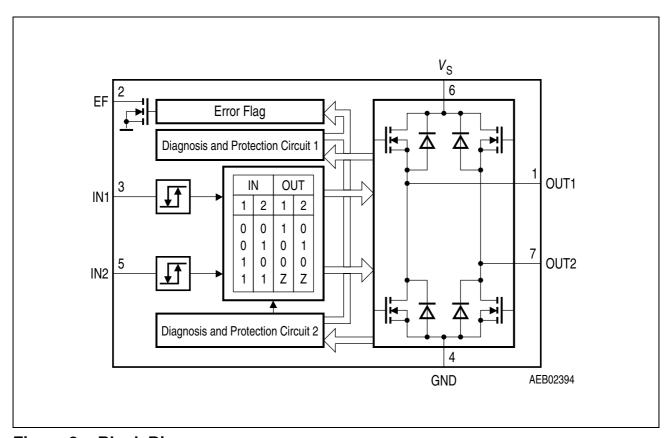


Figure 2 Block Diagram



1.5 Circuit Description

Input Circuit

The control inputs consist of TTL/CMOS-compatible schmitt-triggers with hysteresis. Buffer amplifiers are driven by this stages.

Output Stages

The output stages consist of a DMOS H-bridge. Integrated circuits protect the outputs against short-circuit to ground and to the supply voltage. Positive and negative voltage spikes, which occur when switching inductive loads, are limited by integrated freewheeling diodes.

A monitoring circuit for each output transistor detects whether the particular transitor is active and in this case prevents the corresponding source transistor (sink transistor) from conducting in sink operation (source operation). Therefore no crossover currents can occur.

1.6 Input Logic Truth Table

Functional Truth Table

IN1	IN2	OUT1	OUT2	Comments
L	L	Н	L	Motor turns clockwise
L	Н	L	Н	Motor turns counterclockwise
Н	L	L	L	Brake; both low side transistors turned-ON
Н	Н	Z	Z	Open circuit detection

Notes for Output Stage

Symbol	Value
L	Low side transistor is turned-ON High side transistor is turned-OFF
Н	High side transistor is turned-ON Low side transistor is turned-OFF
Z	High side transistor is turned-OFF Low side transistor is turned-OFF



1.7 Monitoring Functions

Undervoltage lockout (UVLO):

When $V_{\rm S}$ reaches the switch on voltage $V_{\rm S\,ON}$ the IC becomes active with a hysteresis. All output transistors are switched off if the supply voltage $V_{\rm S\,OFF}$ drops below the switch off value $V_{\rm S\,OFF}$.

1.8 Protective Function

Various errors like short-circuit to + $V_{\rm S}$, ground or across the load are detected. All faults result in turn-OFF of the output stages after a delay of 50 μs and setting of the error flag EF to ground. Changing the inputs resets the error flag.

a. Output Shorted to Ground Detection

If a high side transistor is switched on and its output is shorted to ground, the output current is internally limited. After a delay of 50 μ s all outputs will be switched-OFF and the error flag is set.

b. Output Shorted to + $V_{\rm S}$ Detection

If a low side transistor is switched on and its output is shorted to the supply voltage, the output current is internally limited. After a delay of 50 μ s all outputs will be switched-OFF and the error flag is set.

c. Overload Detection

An internal circuit detects if the current through the low side transistor exceeds the trippoint I_{SDI} . In this case all outputs are turned off after 50 μ s and the error flag is set.

d. Overtemperature Protection

At a junction temperature higher than 150 °C the thermal shutdown turns-OFF, all four output stages commonly and the error flag is set with a delay.

e. Open Load Detection

The output Q1 has a 10 k Ω pull-up resistor and the output Q2 has a 10 k Ω pull-down resistor. If E1 and E2 are high, all output power stages are turned-OFF. In case of no load between Q1 and Q2 the output voltage Q1 is $V_{\rm S}$ and Q2 is ground. This state will be detected by two comparators and an error flag will be set after a delay time of 50 μ s. Changing the inputs resets the error flip flop.



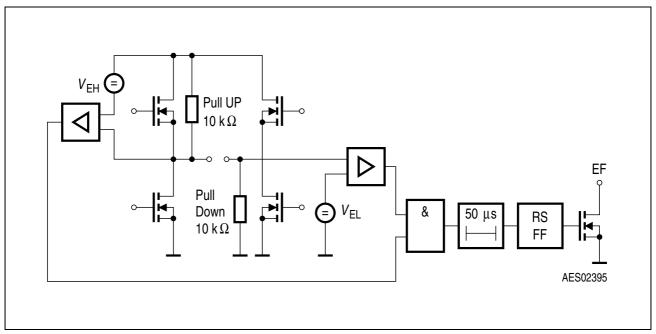


Figure 3 Simplified Schematic for Open Load Detection



Diagnosis

2 Diagnosis

Various errors as listed in the table "Diagnosis" are detected. Short circuits and overload result in turning off the output stages after a delay $t_{\rm dSD}$ and setting the error flag simultaneously [EF = L]. Changing the inputs to a state where the fault is not detectable resets the error flag (input toggling) with the exception of short circuit from OUT1 to OUT2 (load short circuit).

Flag	IN1	IN2	OUT1	OUT2	EF	Remarks	Nr.
	0	0	Н	L	1	Not detectable	1
Open circuit between OUT1 and OUT2	0	1	L	Н	1	Not detectable	2
	1	0	L	L	1	Not detectable	3
	1	1	Z	Z	0		4
	0	0	$V_{\rm s}$ /2	$V_{\rm s}$ /2	0		5
Short circuit from OUT1 to OUT2	0	1	$V_{ m s}$ /2	$V_{ m s}$ /2	0		6
	1	0	L	L	1	Not detectable	7
	1	1	Z	Z	1	Not detectable	8
	0	0	GND	L	0		9
Short circuit from OUT1 to GND	0	1	GND	Н	1	Not detectable	10
	1	0	GND	L	1	Not detectable	11
	1	1	GND	L	1	Not detectable	12
	0	0	Н	GND	1	Not detectable	13
Short circuit from OUT2 to GND	0	1	L	GND	0		14
	1	0	L	GND	1	Not detectable	15
	1	1	L	GND	1	Not detectable	16
	0	0	$V_{ extsf{s}}$	L	1	Not detectable	17
Short circuit from OUT1 to $V_{ m s}$	0	1	$V_{ extsf{s}}$	Н	0		18
	1	0	$V_{ t s}$	Н	0		19
	1	1	$V_{ extsf{s}}$	Н	1	Not detectable	20
	0	0	Н	$V_{ extsf{s}}$	0		21
Short circuit from OUT2 to $V_{ m s}$	0	1	L	$V_{ extsf{s}}$	1	Not detectable	22
	1	0	Н	$V_{ extsf{s}}$	0		23
	1	1	Н	$V_{ extsf{S}}$	1	Not detectable	24
Overtemperature or undervoltage	0	0	Z	Z	0		25
	0	1	Z	Z	0		26
	1	0	Z	Z	0		27
	1	1	Z	Z	0		28

IN: 0 = Logic LOW OUT: Z = Output in tristate condition EF: 1 = No error 1 = Logic HIGH $= V_s/2$ due to internal Pull-up/down resistors 0 = Error

L = Output in sink condition
H = Output in source condition



3 Electrical Characteristics

3.1 Absolute Maximum Ratings

 $-40 \, ^{\circ}\text{C} < T_{\text{j}} < 150 \, ^{\circ}\text{C}$

Parameter	Symbol	Limit Values		Unit	Remarks
		min.	max.		

Voltages

Supply voltage	V_{S}	- 0.3	40	V	_
		– 1	40	V	$t < 0.5 \text{ s}; I_{S} > -5 \text{ A}$
Logic input voltage	V _{IN1, 2}	- 0.3	7	V	0 V < V _S < 40 V
Diagnostics output voltage	V_{EF}	- 0.3	7	V	_

Currents of DMOS-Transistors and Freewheeling Diodes

Output current (cont.)	I _{OUT1, 2}	- 5	5	Α	_
Output current (peak)	I _{OUT1, 2}	- 6	6	Α	$t_{\rm p}$ < 100 ms; T = 1 s
Output current (peak)	I _{OUT1, 2}	_	_	A	$t_{\rm p}$ < 50 µs; T = 1 s; internally limitted; see overcurrent

Temperatures

Junction temperature	$T_{\rm j}$	- 40	150	°C	_
Storage temperature	T_{stg}	- 50	150	°C	_

Thermal Resistances

Junction case	R_{thjC}	_	3	K/W	P-TO220-7-11/12, P-TO263-7-1
Junction ambient	R_{thjA}	_	65	K/W	P-TO220-7-11/12
		_	75	K/W	P-TO263-7-1
Junction case	R_{thjC}	_	5	K/W	P-DSO-20-12
Junction ambient	R_{thjA}	_	50	K/W	P-DSO-20-12

Note: Maximum ratings are absolute ratings; exceeding any one of these values may cause irreversible damage to the integrated circuit.



3.2 Operating Range

Parameter	Symbol	Limit Values		Unit	Remarks
		min.	max.		
Supply voltage	V_{S}	V_{UVON}	40	V	After $V_{\rm S}$ rising above $V_{\rm UVON}$
Supply voltage increasing		- 0.3	V_{UVON}	V	Outputs in tristate
Supply voltage decreasing		- 0.3	V_{UVOFF}	V	condition
Logic input voltage	V _{IN1, 2}	- 0.3	7	V	-
Junction temperature	T_{j}	- 40	150	°C	_

3.3 Electrical Characteristics

6 V < $V_{\rm S}$ < 18 V; IN1 = IN2 = HIGH

 $I_{\rm OUT1,\,2} = 0$ A (No load); $-40~{\rm ^{\circ}C} < T_{\rm j} < 150~{\rm ^{\circ}C}$; unless otherwise specified

Parameter	Symbol	Lir	nit Valu	ues	Unit	Test Condition
		min.	typ.	max.		

Current Consumption

Quiescent current	I_{S}	_	_	10	mA	IN1 = IN2 = LOW;
						$V_{\rm S}$ = 13.2 V

Under Voltage Lockout

UV-Switch-ON voltage	V_{UVON}	_	5.3	6	V	$V_{ m S}$ increasing
UV-Switch-OFF voltage	V_{UVOFF}	3.5	4.7	5.6	V	$V_{ m S}$ decreasing
UV-ON/OFF-Hysteresis	V_{UVHY}	0.2	0.6	_	V	$V_{ m UVON}-V_{ m UVOFF}$



3.3 Electrical Characteristics (cont'd)

6 V < $V_{\rm S}$ < 18 V; IN1 = IN2 = HIGH

 $I_{\rm OUT1,\,2} = 0$ A (No load); -40 °C < $T_{\rm j}$ < 150 °C; unless otherwise specified

Parameter	Symbol	Lir	nit Valu	ıes	Unit	Test Condition
_		min.	typ.	max.		

Outputs OUT1, 2

Static Drain-Source-On Resistance

Source $I_{\text{OUT}} = -3 \text{ A}$	R_{DSONH}	_	220	350	mΩ	$6 \text{ V} < V_{\text{S}} < 18 \text{ V}$ $T_{\text{j}} = 25 \text{ °C}$
			_	500	mΩ	6 V < V _S < 18 V
			350	500	mΩ	$V_{\text{S ON}} < V_{\text{S}} \le 6 \text{ V}$ $T_{\text{j}} = 25 \text{ °C}$
			_	800	mΩ	$V_{\rm S~ON} < V_{\rm S} \le 6~{ m V}$
Sink $I_{\text{OUT}} = 3 \text{ A}$	R_{DSONL}	_	230	350	mΩ	$6 \text{ V} < V_{\text{S}} < 18 \text{ V}$ $T_{\text{j}} = 25 \text{ °C}$
			_	500	mΩ	6 V < V _S < 18 V
			400	600	mΩ	$V_{\text{S ON}} < V_{\text{S}} \le 6 \text{ V}$ $T_{\text{j}} = 25 \text{ °C}$
			_	1000	mΩ	$V_{\rm S~ON} < V_{\rm S} \le 6~{ m V}$

Note: Values of $R_{DS\ ON}$ for $V_{S\ ON} < V_S \le 6$ V are guaranteed by design.

Overcurrent

Source shutdown trippoint	$-I_{SDH}$	_	_	10	Α	$T_{\rm j}$ = $-$ 40 °C
		_	8	_	Α	<i>T</i> _j = 25 °C
		6	_	_	Α	$T_{\rm j}$ = 150 °C
Sink shutdown trippoint	I_{SDL}	_	_	10	Α	$T_{\rm j}$ = $-$ 40 °C
		_	8	_	Α	<i>T</i> _j = 25 °C
		6	_	_	Α	<i>T</i> _j = 150 °C
Shutdown delay time	$t_{\sf dSD}$	25	50	80	μs	_



3.3 Electrical Characteristics (cont'd)

6 V < $V_{\rm S}$ < 18 V; IN1 = IN2 = HIGH

 $I_{\text{OUT1, 2}} = 0$ A (No load); $-40 \, ^{\circ}\text{C} < T_{\text{j}} < 150 \, ^{\circ}\text{C}$; unless otherwise specified

Parameter	Symbol	Limit Values			Unit	Test Condition
		min.	typ.	max.		

Short Circuit Current Limitation

Source current	$-I_{SCH}$	_	_	20	А	$t < t_{\rm dSD}$
Sink current	I_{SCL}	_	_	15	Α	$t < t_{dSD}$

Open Circuit

Pull up resistor	$R_{\sf UP}$	5	10	20	kΩ	_
Pull down resistor	R_{DOWN}	5	10	20	kΩ	_
Switching threshold H	V_{EH}	2	2.5	3	٧	_
Switching threshold L	V_{EH}	2	2.4	3	V	_
Detection delay time	$t_{\sf dSD}$	25	50	80	μs	_

Output Delay Times (Device Active for t > 1 ms)

Source ON	t _{d ON H}	_	10	20	μs	$I_{\text{OUT}} = -3 \text{ A}$ resistive load
Sink ON	t _{d ON L}	_	10	20	μs	I _{OUT} = 3 A resistive load
Source OFF	t _{d OFF H}	_	2	5	μs	$I_{\text{OUT}} = -3 \text{ A}$ resistive load
Sink OFF	t _{d OFF L}	_	2	5	μs	I _{OUT} = 3 A resistive load



3.3 Electrical Characteristics (cont'd)

6 V < $V_{\rm S}$ < 18 V; IN1 = IN2 = HIGH

 $I_{\rm OUT1,~2}$ = 0 A (No load); – 40 °C < $T_{\rm j}$ < 150 °C; unless otherwise specified

Parameter	Symbol	Lir	nit Valu	ıes	Unit	Test Condition
		min.	typ.	max.		

Output Switching Times (Device Active for t > 1 ms)

Source ON	t _{ON H}	_	15	30	μs	$I_{\text{OUT}} = -3 \text{ A}$ resistive load
Sink ON	t _{ON L}	_	5	10	μs	I _{OUT} = 3 A resistive load
Source OFF	t _{OFF H}	_	2	5	μs	$I_{\text{OUT}} = -3 \text{ A}$ resistive load
Sink OFF	t _{OFF L}	_	2	5	μs	I _{OUT} = 3 A resistive load

Clamp Diodes

Forward Voltage

High-side	V_{FH}	_	1	1.5	V	<i>I</i> _F = 3 A
Low-side	V_{FL}	_	1.1	1.5	V	$I_{F} = 3 \; A$

Leakage Current

Source	I_{LKH}	- 100	- 50	_	μΑ	OUT1 = $V_{\rm S}$
Sink	I_{LKL}	_	50	100	μΑ	OUT2 = GND

Logic

Control Inputs IN 1, 2

H-input voltage threshold	V_{INH}	2.8	2.5	_	V	_
L-input voltage	V_{INL}	_	1.7	1.2	V	_
Hysteresis of input voltage	V_{INHY}	0.4	0.8	1.2	V	_
H-input current	I_{INH}	-2	0	2	μΑ	V_{IN} = 5 V
L-input current	I_{INL}	– 10	-4	0	μΑ	$V_{IN} = 0 \; V$



3.3 Electrical Characteristics (cont'd)

6 V < $V_{\rm S}$ < 18 V; IN1 = IN2 = HIGH

 $I_{\rm OUT1,\,2} = 0$ A (No load); $-40~{\rm ^{\circ}C} < T_{\rm j} < 150~{\rm ^{\circ}C}$; unless otherwise specified

Parameter	Symbol	Limit Values		Unit	Test Condition	
		min.	typ.	max.		

Error Flag Output EF

Low output voltage	V_{EFL}	_	0.25	0.5	V	$I_{EF} = 3 \; mA$
Leakage current	I_{EFL}	_	_	10	μΑ	V_{EF} = 7 V

Thermal Shutdown

Thermal shutdown junction temperature	T_{jSD}	150	175	200	°C	_
Thermal switch-on junction temperature	T_{jSO}	120	_	170	°C	_
Temperature hysteresis	ΔT	_	30	_	K	_
Shutdown delay time	$t_{\sf dSD}$	25	50	80	μs	_

Note: Values of thermal shutdown are guaranteed by design.



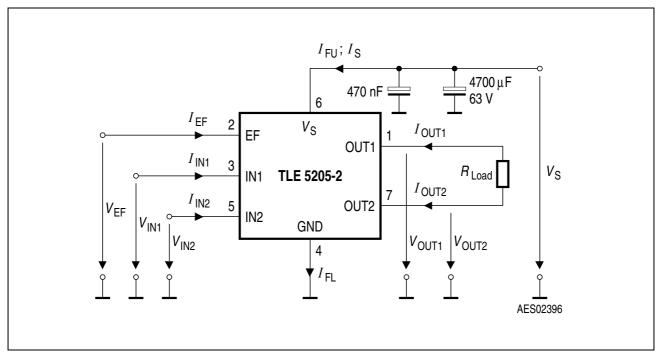


Figure 4 Test Circuit

	Overcurrent	Short Circuit	Open Circuit
I_{OUT}	I_{SD}	I_{SC}	I_{OC}



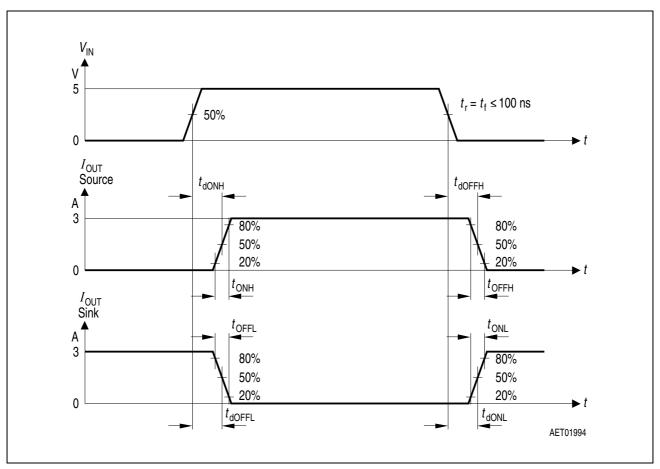


Figure 5 Switching Time Definitions

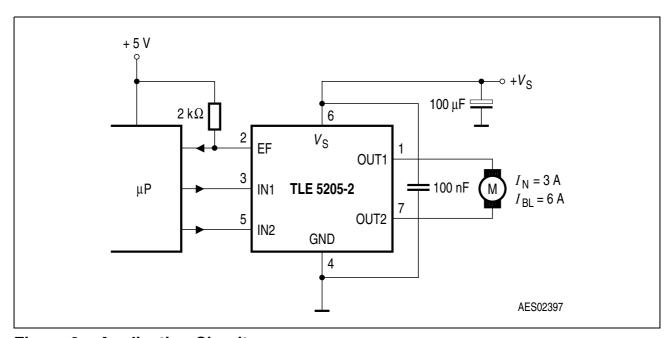


Figure 6 Application Circuit



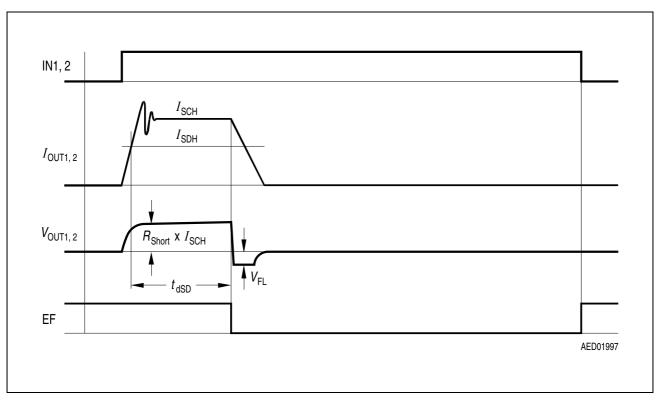


Figure 7 Timing Diagram for Output Shorted to Ground

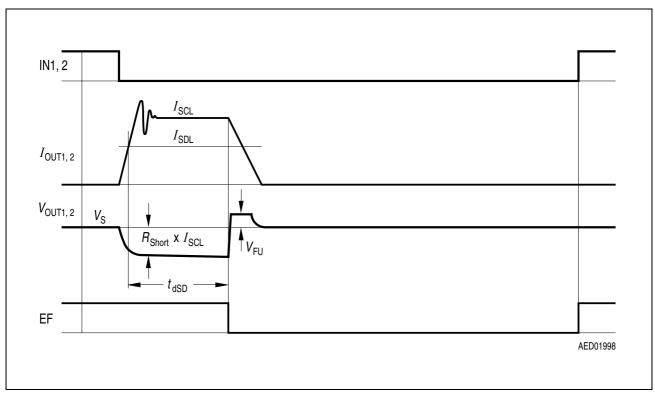
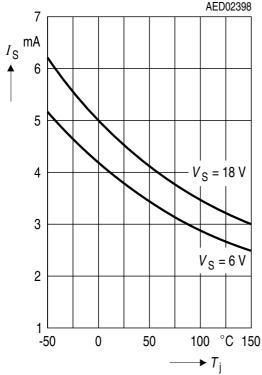


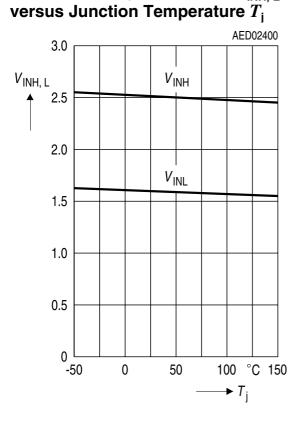
Figure 8 Timing Diagram for Output Shorted to V_{S}



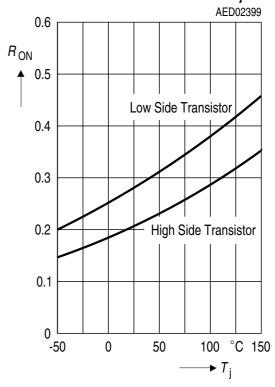
Diagrams Quiescent Current $I_{\rm S}$ (Active) versus Junction Temperature $T_{\rm i}$



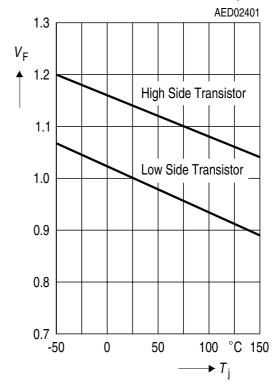
Input Switching Thresholds $V_{\mathsf{INH.\ L}}$



Static Drain-Source ON-Resistance versus Junction Temperature $T_{\rm i}$

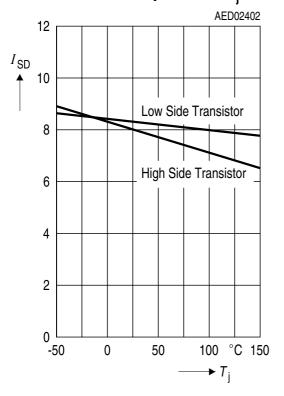


Clamp Diode Forward Voltage V_{F} versus Junction Temperature T_{i}

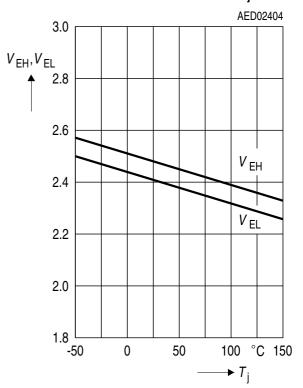




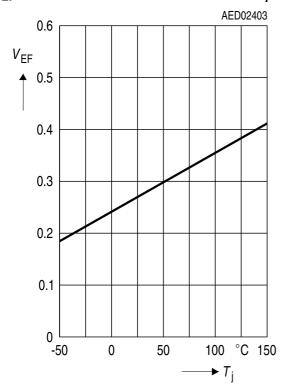
Overcurrent Shutdown Threshold $I_{\rm SD}$ versus Junction Temperature $T_{\rm i}$



Switching Threshold $V_{\rm EH},\,V_{\rm EH}$ versus Junction Temperature $T_{\rm j}$

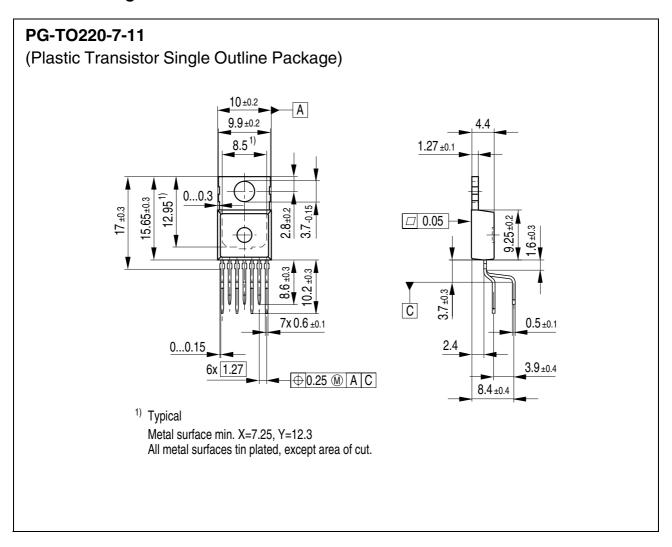


Error-Flag Saturation Output Voltage V_{EF} versus Junction Temperature T_{i}





4 Package Outlines



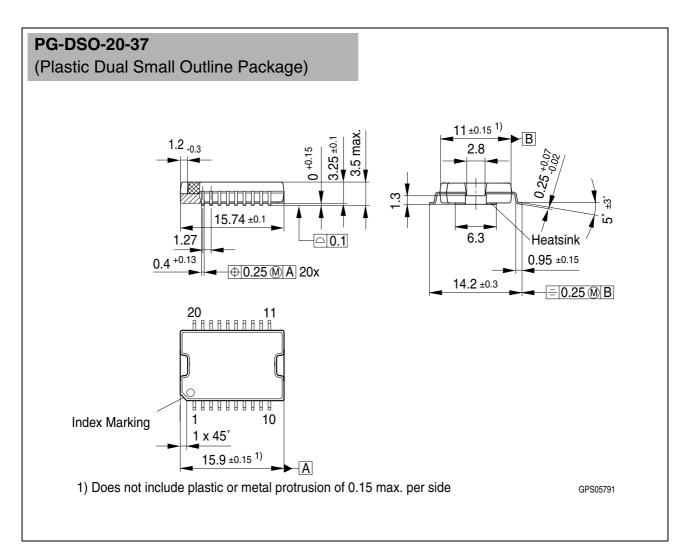
Green Product (RoHS compliant)

To meet the world-wide customer requirements for environmentally friendly products and to be compliant with government regulations the device is available as a green product. Green products are RoHS-Compliant (i.e Pb-free finish on leads and suitable for Pb-free soldering according to IPC/JEDEC J-STD-020).

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SMD = Surface Mounted Device





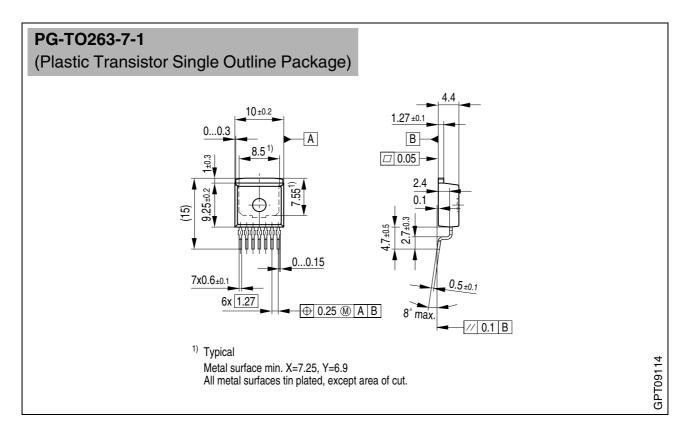
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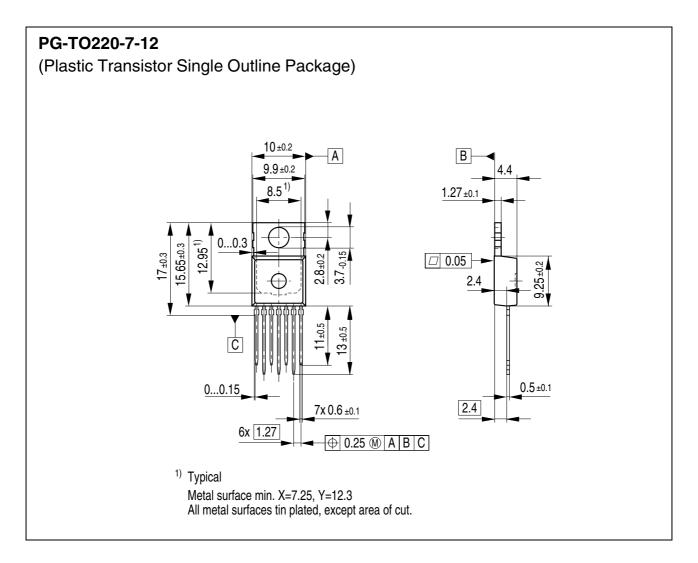
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Revision History

5 Revision History

Version	Date	Changes
Rev. 1.1	2007-07-31	 RoHS-compliant version of the TLE 5205-2 All pages: Infineon logo updated Page 1: "AEC qualified" and "RoHS" logo added, "Green Product (RoHS compliant)" and "AEC qualified" statement added to feature list, package names changed to RoHS compliant versions, package pictures updated, ordering codes removed Page 20-23: Package names changed to RoHS compliant versions, "Green Product" description added Revision History added Legal Disclaimer added

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